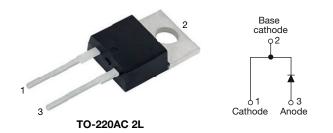
Vishay Semiconductors

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Hyperfast Rectifier, 15 A FRED Pt[®]



PRIMARY CHARACTERISTICS						
I _{F(AV)} 15 A						
V _R	600 V					
V _F at I _F	1.55 V					
t _{rr} (typ.)	18 ns					
T _J max.	175 °C					
Package	TO-220AC 2L					
Circuit configuration	Single					

FEATURES

- Hyperfast recovery time, extremely low Q_{rr}
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- True 2 pin package
- Designed and qualified according to JEDEC[®]-JESD 47
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

The extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

ABSOLUTE MAXIMUM RATINGS								
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS				
Peak repetitive reverse voltage	V _{RRM}		600	V				
Average rectified forward current in DC	I _{F(AV)}	T _C = 141 °C	15	^				
Non-repetitive peak surge current	I _{FSM}	T _J = 25 °C	120	A				
Operating junction and storage temperatures	T _J , T _{Stg}		-65 to +175	°C				

ELECTRICAL SPECIFICATIONS (T _J = 25 $^{\circ}$ C unless otherwise specified)								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Breakdown voltage, blocking voltage	V _{BR} , V _R			-	-			
Forward voltage	V _F	I _F = 15 A	-	2.5	3.4	3.4 V		
Forward voltage		I _F = 15 A, T _J = 150 °C	-	1.55	2			
		$V_{R} = V_{R}$ rated	-	0.02	36			
Reverse leakage current I _R		$T_J = 150 \text{ °C}, V_R = V_R \text{ rated}$	-	40	250	μA		
Junction capacitance	CT	V _R = 600 V	-	12	-	pF		
Series inductance	L _S	Measured lead to lead 5 mm from package body	-	8	-	nH		



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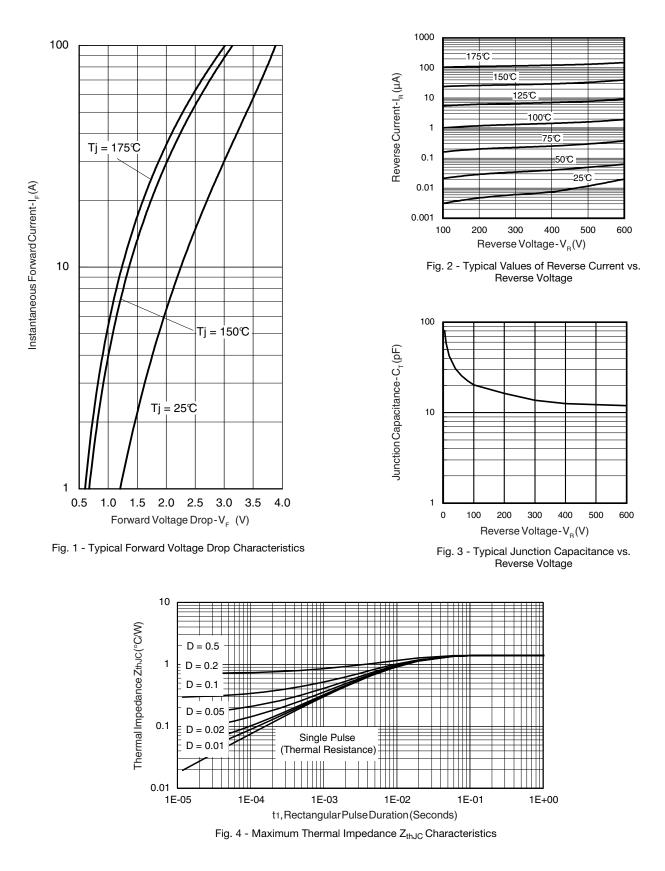
DYNAMIC RECOVERY CHARACTERISTICS ($T_J = 25 \text{ °C}$ unless otherwise specified)									
PARAMETER	SYMBOL	TEST CO	NDITIONS	MIN.	TYP.	MAX.	UNITS		
		$I_F = 1 \text{ A}, \ dI_F/dt = 100$	A/ μ s, V _R = 30 V	-	17	23			
Reverse recovery time	+	I _F = 15 A, dI _F /dt = 10	0 A/µs, V _R = 30 V	-	18	30	20		
Reverse recovery time	t _{rr}	T _J = 25 °C		-	20	-	ns		
		T _J = 125 °C	l _F = 15 A, dl _F /dt = 200 A/μs, V _R = 390 V	-	45	-			
Peak recovery current		T _J = 25 °C		-	2.7	-	А		
Feak recovery current	I _{RRM}	T _J = 125 °C		-	5.5	-	A		
	0	T _J = 25 °C		-	26	-	nC		
Reverse recovery charge	Q _{rr}	T _J = 125 °C		-	130	-	no		
Reverse recovery time	t _{rr}		I _F = 15 A,	-	32	-	ns		
Peak recovery current	I _{RRM}	T _J = 125 °C	dl _F /dt = 800 A/µs,	-	17	-	А		
Reverse recovery charge	Q _{rr}		V _R = 390 V	-	290	-	nC		

THERMAL - MECHANICAL SPECIFICATIONS								
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS		
Maximum junction and storage temperature range	T _J , T _{Stg}		-65	-	175	°C		
Thermal resistance,	P		-	1.2	1.4			
junction-to-case	R _{thJC}		-	3.7	4.3	Ĩ		
Thermal resistance, junction to ambient	R _{thJA}	Typical socket mount	-	-	70	°C/W		
Typical thermal resistance, case to heatsink	R _{thCS}	Mounting surface, flat, smooth, and greased	-	0.5	-	-		
Woight			-	2	-	g		
Weight			-	0.07	-	oz.		
Mounting torque			6 (5)	-	12 (10)	kgf · cm (lbf · in)		
Marking device		Case style TO-220AC 2L	ETX1506					



VS-ETX1506-M3

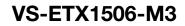
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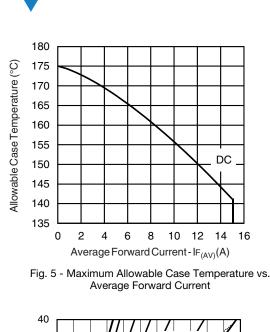
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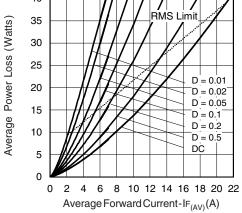


Fig. 6 - Forward Power Loss Characteristics

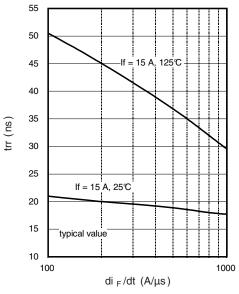


Fig. 7 - Typical Reverse Recovery vs. dl_F/dt

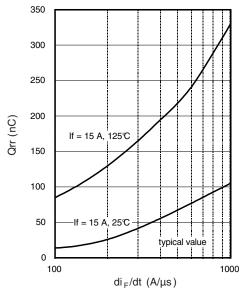


Fig. 8 - Typical Stored Charge vs. dI_F/dt

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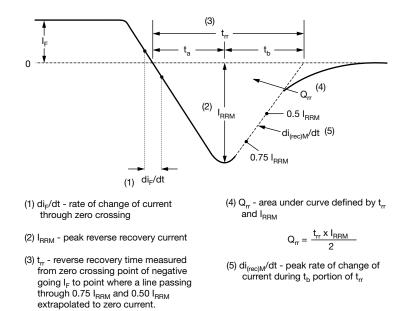


Fig. 9 - Reverse Recovery Waveform and Definitions

ORDERING INFORMATION TABLE

SHAY

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Device code	VS-	Е	т	x	15	06	-M3
		2	3	4	5	6	7
	1 2		nay Sem			oduct	
		E =	cuit conf single	-	n:		
			2L TO-2 hyperfa		/ery time	e	
			rent coo tage coo				
	7		ironmer	0			
		-IVIS	3 = halo	gen-tree	, Rohs	-compil	iant, and

ORDERING INFORMATION (Example)							
PREFERRED P/N BASE QUANTITY PACKAGING DESCRIPTION							
VS-ETX1506-M3	50	Antistatic plastic tubes					

LINKS TO RELATED DOCUMENTS					
Dimensions	www.vishay.com/doc?96156				
Part marking information	www.vishay.com/doc?95391				

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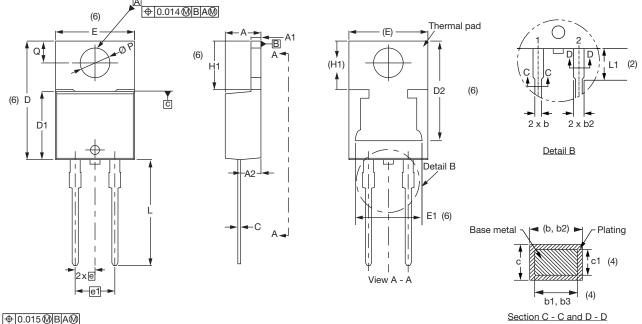
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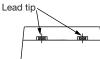


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2L TO-220AC

DIMENSIONS in millimeters and inches





SYMBOL	MILLIN	IETERS	INC	HES	NOTES
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES
А	4.25	4.65	0.167	0.183	
A1	1.14	1.40	0.045	0.055	
A2	2.50	2.92	0.098	0.115	
b	0.69	1.01	0.027	0.040	
b1	0.38	0.97	0.015	0.038	4
b2	1.20	1.73	0.047	0.068	
b3	1.14	1.73	0.045	0.068	4
С	0.36	0.61	0.014	0.024	
c1	0.36	0.56	0.014	0.022	4
D	14.85	15.35	0.585	0.604	3
D1	8.38	9.02	0.330	0.355	

Conforms to JEDEC®	outline	TO-220AC
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SYMBOL	MILLIN	IETERS	INC	INCHES			
STMBOL	MIN.	MAX.	MIN.	MAX.	NOTES		
D2	11.68	13.30	0.460	0.524	6, 7		
E	10.11	10.51	0.398	0.414	3, 6		
E1	6.86	8.89	0.270	0.350	6		
е	2.41	2.67	0.095	0.105			
e1	4.88	5.28	0.192	0.208			
H1	6.09	6.48	0.240	0.255	6		
L	13.52	14.02	0.532	0.552			
L1	3.32	3.82	0.131	0.150	2		
ØР	3.54	3.91	0.139	0.154			
Q	2.60	3.00	0.102	0.118			

Notes

 $^{(1)}\,$ Dimensioning and tolerancing as per ASME Y14.5M-1994

⁽²⁾ Lead dimension and finish uncontrolled in L1

⁽⁴⁾ Dimension b1, b3, and c1 apply to base metal only

(5) Controlling dimensions: inches

- ⁽⁶⁾ Thermal pad contour optional within dimensions E, H1, D2, and E1
- ⁽⁷⁾ Outline conforms to JEDEC[®] TO-220, except D2

Revision: 13-Jun-2019

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⁽³⁾ Dimension D, D1, and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body



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